Multi-Port SFP Connectors

product line.

Molex is rapidly expanding its Small Form-factor Pluggable (SFP) product offering to meet the demands of networking and storage industries, which require denser and faster packaging for high-speed serial interfaces. The new SFP Stacked Multi-Port Connectors are the latest additions to Molex's extensive SFP

These new connectors offer high port density with complete integration of stacked 20-circuit SFP connector ports within a cage. Integrated lightpipes are available to provide port-status indication to the user. The product line encompasses connectors offered in two heights and is available in five port configurations:

2-by-1, 2-by-2, 2-by-4, 2-by-5 and 2-by-6.

Contact Molex for additional information.

High-speed contact design meets 4.25Gbps SFP

configurations (2, 4, 8, 10 and 12) providing

greater port density and reduced PCB assembly

Connectors are available in multiple port

requirements and is capable of speeds up to 10Gbps

Molex's SFP Stacked Multi-Port Connectors accept SFP MSA-compliant modules, allowing installers to configure and upgrade high-speed Ethernet and Fibre Channel (FC) ports. Tin/Lead press-fit connector tails are provided as the standard option. Tin-plated tails will also be available to meet lead-free requirements.

Upgrade to high-speed Ethernet and Fibre Channel ports with Molex's Stacked



Olex[®] 0.80mm (.031") Pitch SFP Stacked Multi-Port Connectors

75310, 75786, 75460, 75787, 75462, 75640, 75759, 75714, 75454, 75450, 75733, 75734, 75477, 75451



Multi-port connectors with lightpipes

- Integrated lightpipe option, for use with mono or bicolor SMT LED's provides port status and activity feedback
- Modules are oriented "belly-to-belly" when inserted assuring ease of module removal from the port
- Connectors are available in 2 heights: medium 25.50mm (1.000") and tall 29.30mm (1.150"); Medium-height connectors meet industry standard and are consistent with the stacked multi-port modular jack design; Tall-height connector (2-by-1 only) is designed for 1U applications

SPECIFICATIONS

labor

Features and Benefits

Reference Information

Packaging: Tray UL File No.: E29179 CSA File No.: LR19980 Mates With: SFP MSA-compliant modules Designed In: Millimeters

Electrical

Voltage: 120V Current: 0.5A max. Dielectric Withstanding Voltage: 300V Insulation Resistance: 1 Megohm

Mechanical

Insertion Force to PCB: 35.59N (8 lb) per compliant pin, max. Mating Force: 40N (8.99 lb) max. Unmating Force: 11.5N (2.59 lb) max. Durability: 100 cycles

Physical

Housing: High-temperature plastic, Glass-filled Contact: Tin/Brass (Sn/CuZn) Plating: Contact Area — Gold (Au) Solder Tail Area — Tin/Lead (Sn/Pb) or Tin (Sn) Underplating — Nickel (Ni) PCB Thickness: 2.36mm (0.093") Operating Temperature: -40 to +85°C

APPLICATIONS

Networking, Storage and Telecommunication

- Hubs
- Routers
- Servers
- Switches



0.80mm (.031") Pitch SFP Stacked Multi-Port Connectors

75310, 75786, 75460, 75787, 75462, 75640, 75759, 75714, 75454, 75450, 75733, 75734, 75477, 75451



ORDERING INFORMATION

Order No.	Port Configuration	Height	Mounting	Lightpipes	EMI Protection
75310-0001	- - 2-by-1	29.30mm (1.150″)	Through-hole	Yes	Gasket with flange
75786-0001			Press-fit		
75460-0001			Through-hole		Gasket with extended flange
75787-0001					
75462-0001	-	- 25.50mm (1.000") -	Press-fit	No	Spring fingers
75640-0001				Yes	
75759-0001	- 2-by-2			No	
75714-0001				Yes	
75454-0001	- 2-by-4			No	
75450-0001				Yes	
75733-0001	- 2-by-5			No	
75734-0001				Yes	
75477-0001	- 2-by-6			No	
75451-0001				Yes	

Americas Headquarters Lisle, Illinois 60532 U.S.A. 1-800-78MOLEX amerinfo@molex.com Far East North Headquarters Yamato, Kanagawa, Japan 81-462-65-2324 feninfo@molex.com Far East South Headquarters Jurong, Singapore 65-6-268-6868 fesinfo@molex.com European Headquarters Munich, Germany 49-89-413092-0 eurinfo@molex.com Corporate Headquarters 2222 Wellington Ct. Lisle, IL 60532 U.S.A. 630-969-4550 Fax:630-969-1352

Visit our Web site at http://www.molex.com/product/SFP_Stacked_Connectors